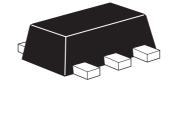
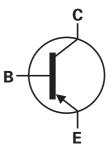


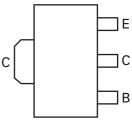
FCX593 SOT89 Silicon planar high voltage transistor

Complementary part number - FMMT493

Device marking - P93







Pinout - top view

Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-base voltage	V _{CBO}	-120	V
Collector-emitter voltage	V _{CEO}	-100	V
Emitter-base voltage	V _{EBO}	-5	V
Peak pulse current	I _{CM}	-2	А
Continuous collector current	۱ _C	-1	А
Base current	۱ _B	-200	mA
Power dissipation at T _{amb} =25°C	P _{tot}	1	W
Operating and storage temperature range	T _j , T _{stg}	-65 to +150	°C

Parameter	Symbol	Min.	Max.	Unit	Conditions
Base breakdown voltages	V _{(BR)CBO}	-120		V	I _C = -100μA
	V _{(BR)CEO}	-100		V	I _C = -10mA ^(*)
	V _{(BR)EBO}	-5		V	I _E = -100μA
Cut-off currents	I _{CBO}		-100	nA	V _{CB} = -100V
	I _{EBO}		-100	nA	V _{EB} = -4V
	I _{CES}		-100	nA	V _{CES} = -100V
Saturation voltages			-0.2	V	I _C = -250mA, I _B = -25mA ^(*)
	V _{CE(sat)}		-0.3	V	l _C = -250mA, l _B = -25mA ^(*)
	V _{BE(sat)}		-1.1	V	I _C = -500mA, I _B = -50mA ^(*)
Base-emitter turn-on voltage	V _{BE(on)}		-1	V	I _C = -1mA, I _B = -5V ^(*)
Static forward current	h _{FE}	100			I _C = -1mA, V _{CE} = -5V
transfer ratio		100			I _C = -250mA, V _{CE} = -5V ^(*)
		100	300		I _C = -500mA, V _{CE} = -5V ^(*)
		50			$I_{C} = -1A, V_{CE} = -5V^{(*)}$
Transition frequency	f _T	50		MHz	I _C = -50mA, V _{CE} = -10V f = 100MHz
Output capacitance	C _{OBO}		5	pF	V _{CB} = -10V, f = 1MHz

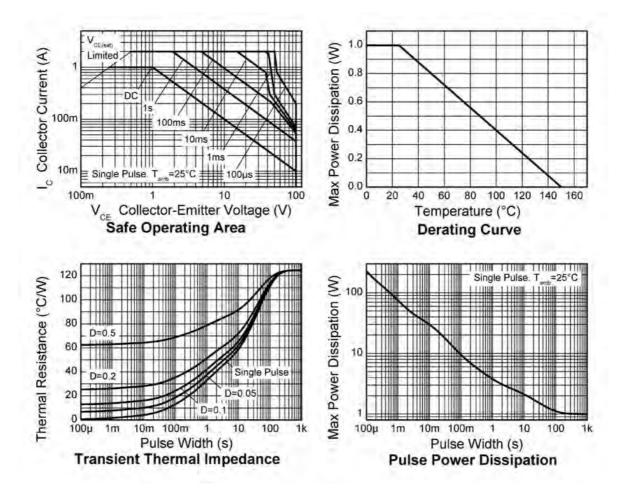
Electrical characteristics (at T_{amb} = 25°C unless otherwise stated)

NOTES:

(*) Measured under pulsed conditions. Pulse width = 300 μ s. Duty cycle \leq 2%.

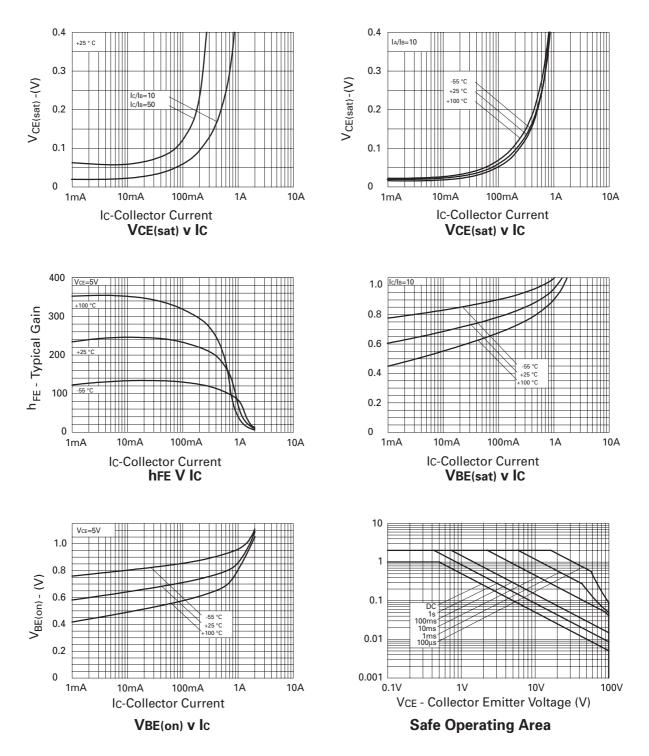
FCX593

Thermal characteristics

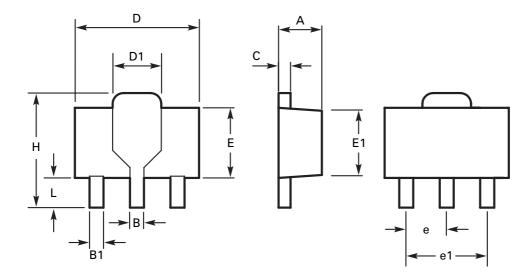


FCX593

Typical characteristics



Package outline - SOT89



DIM	Millim	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Мах
А	1.40	1.60	0.550	0.630	E	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50	BSC	0.059	BSC
С	0.35	0.44	0.014	0.017	e1	3.00	BSC	0.118	BSC
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.52	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

FCX593

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